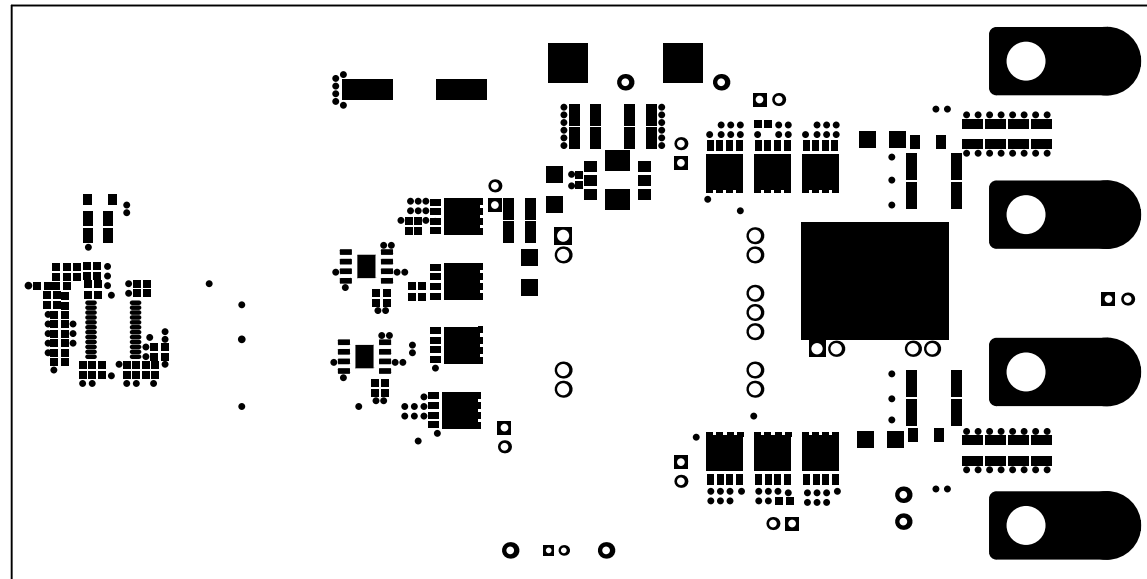
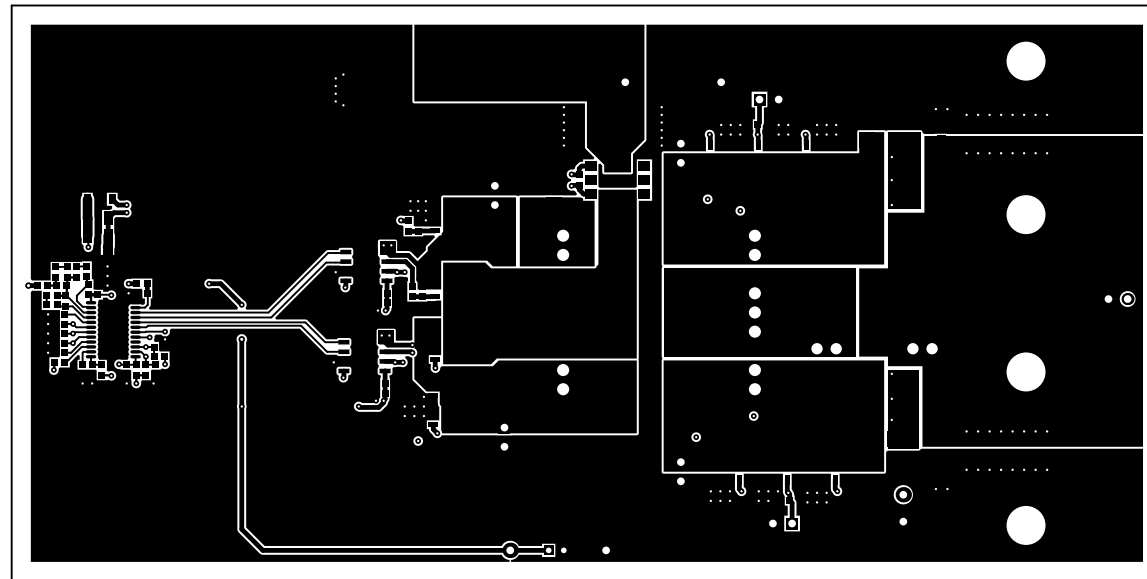


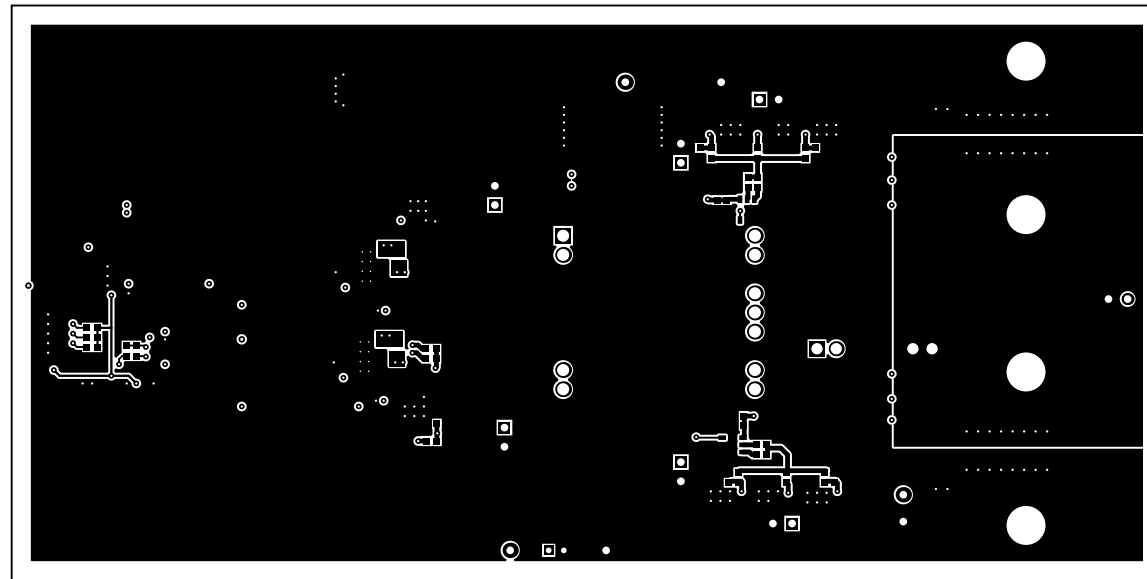
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20657	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #:		
PLOT NAME = Top Overlay	GENERATED : 4/28/2017 10:44:08 AM	TEXAS INSTRUMENTS	



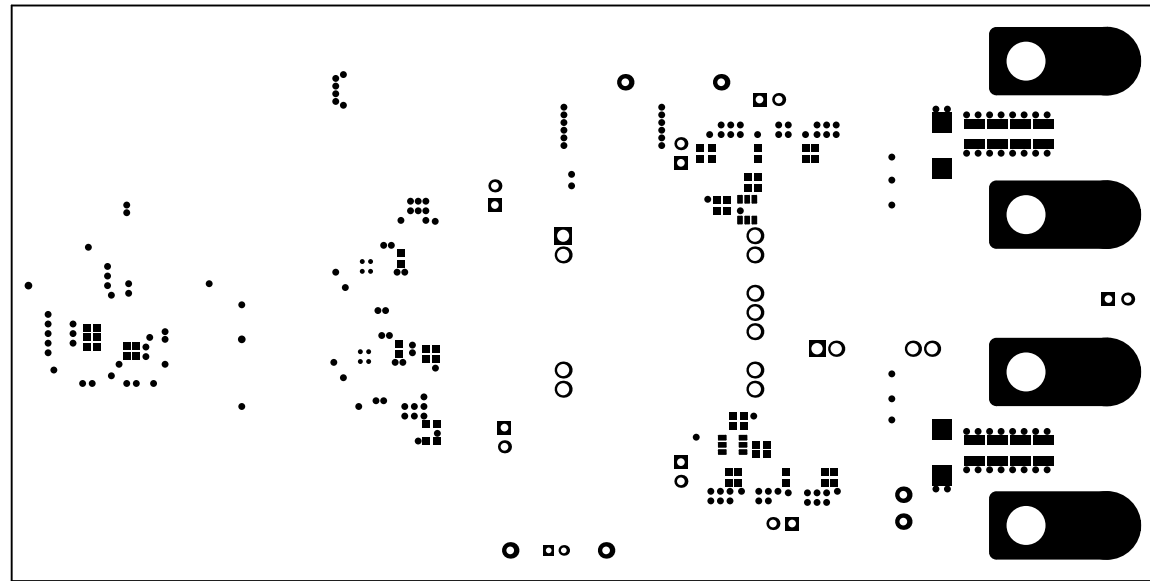
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20657	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #:		
PLOT NAME = Top Solder Mask	GENERATED : 4/28/2017 10:44:09 AM	TEXAS INSTRUMENTS	



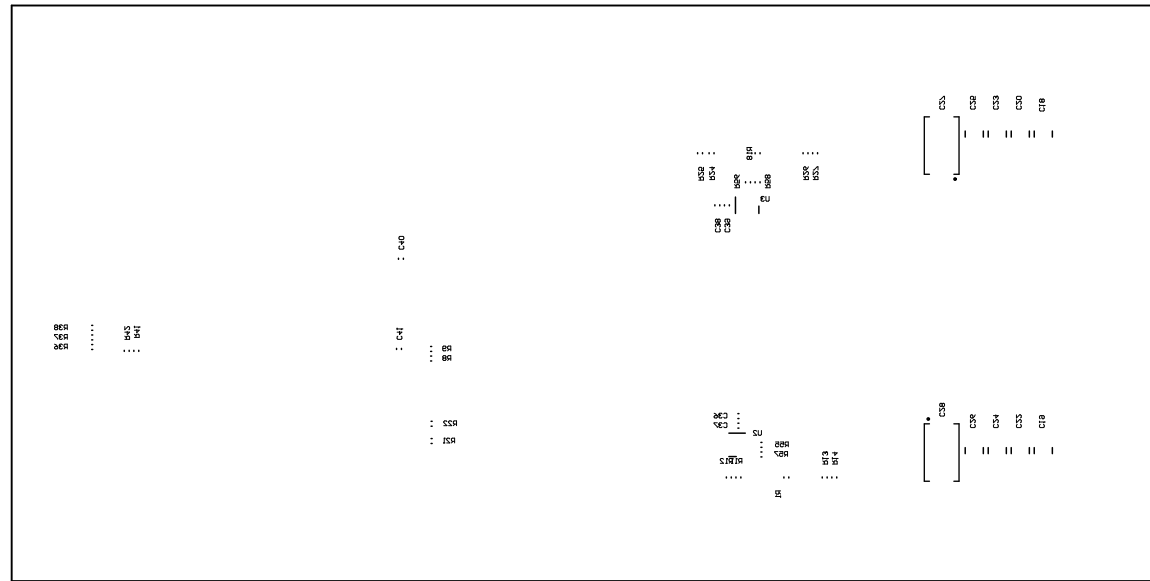
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20657	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #:		
PLOT NAME = Top Layer	GENERATED : 4/28/2017 10:44:09 AM	TEXAS INSTRUMENTS	



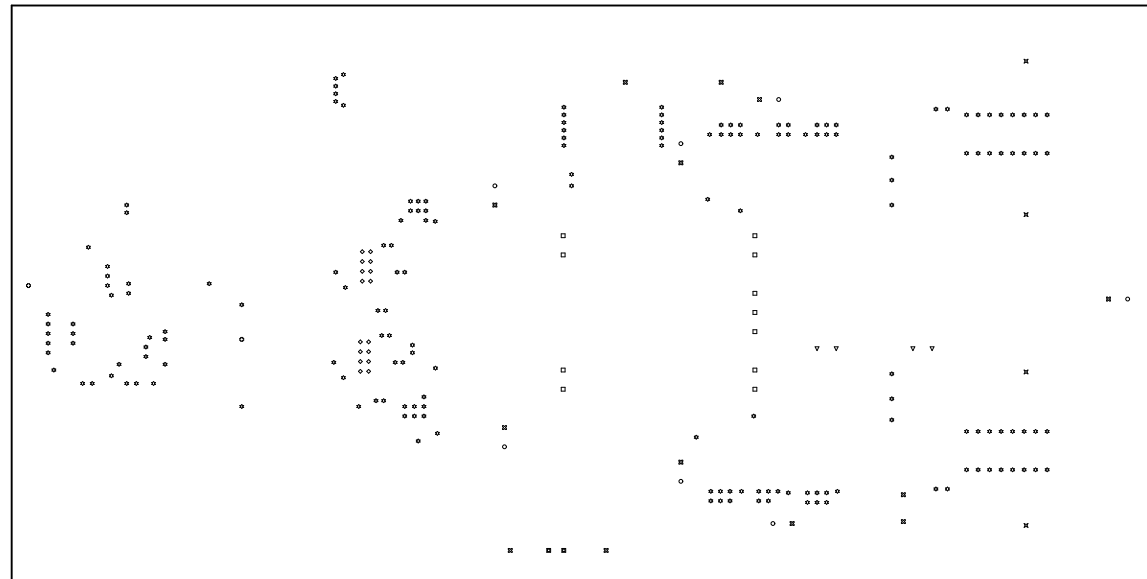
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20657	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #:		
PLOT NAME = Bottom Layer	GENERATED : 4/28/2017 10:44:09 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20657	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #:		
PLOT NAME = Bottom Solder Mask	GENERATED : 4/28/2017 10:44:09 AM	TEXAS INSTRUMENTS	

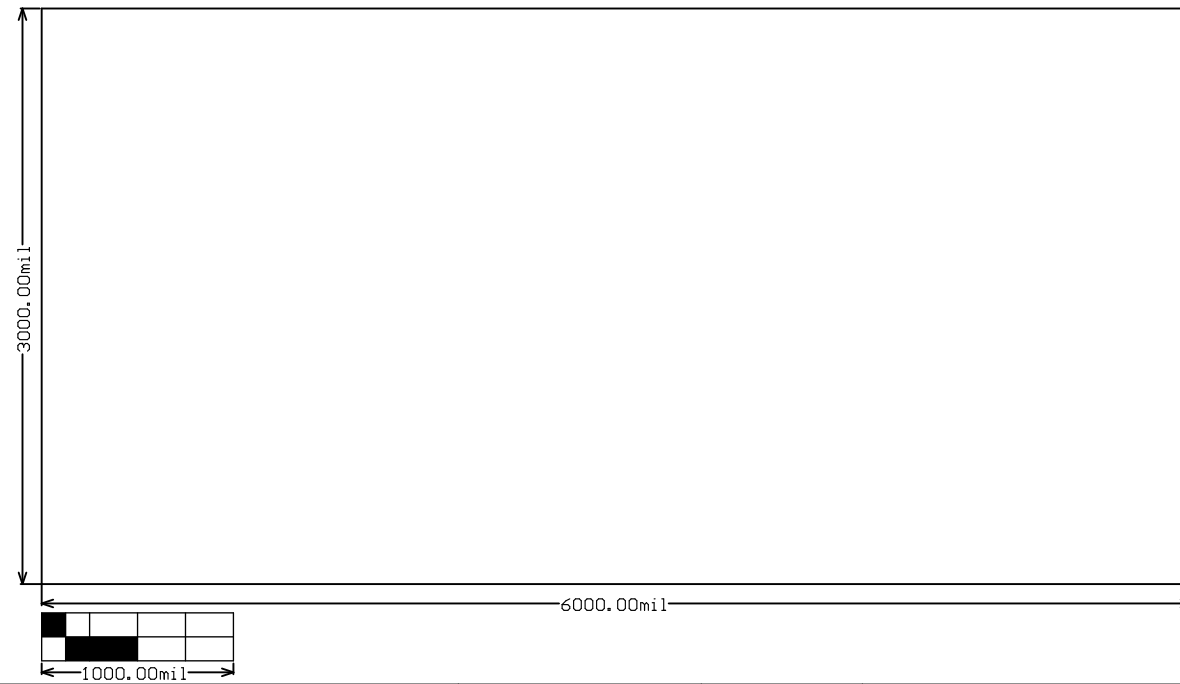


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20657	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #:		
PLOT NAME = Bottom Overlay	GENERATED : 4/28/2017 10:44:09 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
◇	16	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	177	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
⊞	2	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	2	29.53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	
⊞	13	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
○	7	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	59.06mil (1.500mm)	PTH	Round	Top Layer - Bottom Layer	
□	11	62.99mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
⊞	4	203.15mil (5.160mm)	PTH	Round	Top Layer - Bottom Layer	
	236 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20657	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #:		
PLOT NAME = Drill Drawing	GENERATED : 4/28/2017 10:44:09 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20657	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #:		
PLOT NAME = Board Dimensions	GENERATED : 4/28/2017 10:44:10 AM	TEXAS INSTRUMENTS	



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